AN-5081
High Gain Step-up Converter with Coupled Inductor for Piezoelectric Element Drive

Introduction

Recently, the piezoelectric actuator is widely used in many applications especially the mobile devices such as digital cameras and smart phone camera modules due to its compact size and high resolution of the displacement. While the available power source is low-voltage battery in the mobile devices, the high driving voltage is required to drive piezoelectric actuators for high performances. Therefore, a step-up converter is necessary which has high voltage conversion ratio from several volts to several decades or more than one hundred volts.

Conventional step-up dc-dc converters or boost converters are not suitable for high voltage conversion ratio since the effective series resistor (ESR) of the boost inductor prohibits the output voltage from increasing more than 10 times of the input voltage. In this article, a high step-up dc-dc converter with tapped inductor or coupled inductor is introduced and its operational principle and design procedure will be described as well.

For a 1.5 W system with 3 V of the input and 60 V of the output as an example, the experimental results and schematic are given with simple explanation of the full-bridge driver stage of the FAN8831, an optimized control IC including dc-dc step-up converter and full-bridge driver for driving piezoelectric actuators by Fairchild.

Characteristics of Piezoelectric Actuators

Unlike electric motors, piezoelectric actuators convert the electrical energy to the mechanical energy directly with no generation of magnetic field. High resolution of the displacement in sub-nanometer range, excellent dynamic responses, and low power consumption are the advantages of the piezoelectric actuator also [1]. Thus, piezoelectric actuators are used in various applications nowadays.

The piezoelectric actuators are mainly characterized by a non-linear capacitive behavior. Figure 1 shows the impedance curve of a piezoelectric actuator near resonance frequencies. Figure 2 shows the equivalent electrical circuit of a piezoelectric actuator. Van Dyke’s Model [2]. At low frequencies, since the left leg \((R_m-L_m-C_m \text{ in series})\) looks \(C_0\) only due to its high impedance compared to \(L_m\) and \(R_m\), the total impedance is the sum of \(C_0\) and \(C_m\). At the series resonance frequency \(f_r\), the magnitudes of the impedance of \(L_m\) and \(C_m\) are same and their polarities are opposite each other so that the total impedance of the left leg is \(R_m\). Thus, the total impedance of the piezoelectric actuator and the series resonance frequency are as follows:

\[
Z_{f_r} = R_m \parallel Z_{C_m} \approx f_r = \frac{R_m Z_{C_m} \approx f_r}{R_m + Z_{C_m} \approx f_r}
\]

(1)

Ignoring the damping resistor \(R_m\) the locally maximum total impedance occurs at the parallel resonance frequency \(f_o\) as follows:

\[
f_o = \frac{1}{2\pi \sqrt{L_m C_{eq}}}
\]

(2)

At high frequencies, the total impedance will be almost \(C_0\) because the left leg looks \(L_m\) only and the impedance of \(C_0\) is generally lower than that of \(L_m\).

![Figure 1. Impedance of Piezoelectric Actuator Near Resonance Frequencies](image_url)

![Figure 2. Equivalent Electrical Circuit of a Piezoelectric Actuator](image_url)
The capacitance \( C_a \) depends on the area and thickness of the ceramic, as well as on its material properties. It also depends on the number of layers when considering the stacked actuators assembled with thin and laminar wafers of electro-active ceramic material electrically connected in parallel. To get mechanical movement, \( C_a \) should be charged and discharged repeatedly by a driver with an appropriate frequency. Meanwhile, the impedance curve is divided into three regions: capacitive regions for \( f < f_c \) and \( f > f_c \) and inductive region for \( f_c < f < f_e \). For Zero Voltage Switching (ZVS) operation, it is usually recommended to operate in the inductive region since the operating current lags behind the applied voltage to the load. In the piezoelectric actuator, however, the energy in \( L_m \) is not enough to discharge \( C_a \) fully in general so that it is hard to achieve ZVS operation even though the piezoelectric actuator operates in the inductive region. Thus the charging and discharging currents show a large sharp shape in a hard switching manner in any operating frequencies.

The maximum mechanical movement is obtained when operating at the series resonance frequency \( f_r \), since the total impedance of the piezoelectric actuator is the lowest at \( f_r \). Thus it is effective to operate at \( f_r \) and it is required to consider how to improve the hard switching conditions to increase the efficiency by reducing switching losses. It is out of scope of this article but interesting topic.

### Driving Piezoelectric Actuator

To drive piezoelectric actuators from a low-voltage battery in portable devices, a multi-stage converter is needed: a boost stage to get high driving voltage and a bridge stage to drive the piezoelectric actuators effectively, as shown in Figure 3.

![Figure 3. Power Stages to Drive Piezoelectric Actuators from Low-Voltage Battery](image)

Ideal voltage conversion ratio of a conventional boost converter becomes infinity as the duty cycle increases to unity. In practical, however, it is limited due to the boost inductor copper loss. According to [3], the voltage conversion ratio of continuous conduction mode (CCM) operation with the ESR of the boost inductor is as follows:

\[
\frac{V_o}{V_i} = \frac{1}{1 - D \left( 1 + \frac{R_i}{(1 - D)^2 R} \right)}
\]

where \( V \) is the output voltage, \( V_i \) is the input voltage, \( D \) is the duty cycle, \( R \) is the load resistor, and \( R_i \) is the ESR of the boost inductor. The conversion ratio will be decreased as the ratio of \( R_i \) to \( R \) increases. Figure 4 shows the effect of the ESR in a graphical way. It is noticeable that the voltage conversion ratio does not exceed 5 when \( R_i \) is 1% of the load resistor \( R \).

![Figure 4. Voltage Conversion Ratio of a Boost Converter with Inductor Copper Loss (from reference [3])](image)

There are two kinds of piezoelectric actuators in view point of construction: one is a single-layer, and the other is a multi-layer one. The single-layer one is relatively cheap and easily available but its driving voltage is so high up to several hundred voltages in peak-to-peak manner. Meanwhile, the multi-layer piezoelectric actuator has low driving voltage about 20 to 60 V in peak-to-peak manner, but it’s expensive compared to the single-layer one. To make the total system cost low, it is favorable to use a single-layer one. It is required to provide a high driving voltage enough to drive the single-layer piezoelectric actuators even though the available power source is low-voltage battery in the mobile devices. As mentioned ahead, a conventional boost converter is not suitable for driving the single-layer piezoelectric actuators due to its low voltage conversion ratio. Therefore, a step-up converter is necessary which has high voltage conversion ratio from several volts to several decades or more than one hundred volts.

The voltage across the piezoelectric actuators changes its polarity to get the mechanical movement in the bridge stage with the high driving voltage which comes from the output of the high step-up boost stage. While the piezoelectric actuator shows either expansion or contraction with a half-bridge topology, it can be expanded and contracted with positive and negative applied voltage when a full-bridge is used. Therefore, full-bridge topologies as a secondary stage are more favorable to lighten the burden of the boost stage in its voltage conversion ratio point of view.

The FAN8831 is a suitable control IC for driving piezoelectric actuators manufactured by Fairchild. It contains both of two stages depicted in Figure 3. The Critical Conduction Mode (CRM) operated boost controller is integrated with a power MOSFET which has 36 V of the voltage rating. Many protection functions such as Over-Voltage Protection (OVP), Over-Current Protection (OCP), and Thermal Shutdown (TSD) are included in the boost controller as well. As a full-bridge stage, four high-voltage (75 V) rated MOSFETs are integrated: two are low-side driven and the others are high-side driven with high-side gate drivers. The shoot-
through prevention function is also included in the full-bridge stage. All of them are realized in QFN package sized 4 mm by 4 mm with 0.9 mm of the height.

In the next chapter, a high step-up dc-dc converter with tapped inductor or coupled inductor, a well-known topology is introduced. Its operational principle and design procedure is described as well.

**High-Voltage Conversion Ratio Boost Converter with Coupled Inductor**

**Operational Principles**

As described in the previous chapter, a conventional boost converter provides limited output voltage due to the copper loss of the inductor. Moreover, the duty cycle should be increased near to unity to get a large voltage conversion ratio. It requires a smaller inductance, resulting in the high current stress on the main switch and high conduction losses. Since the output voltage is imposed on the main switch when turned off, the voltage stress is also high and so does the switching losses. Figure 5 shows the disadvantages of the conventional boost converter.

Figure 5. (a) Conventional Boost Converter and (b) its Inductor Current Waveforms when Duty Cycles Increases for Higher \( V_O \)

To overcome these shortcomings, lots of topologies have been proposed. Among them the coupled inductor boost converter has attracted a lot of attention due to the high voltage conversion ratio, no additional components, the simple winding structure in the inductor, and low voltage stress on the main switch. [4]-[7].

Figure 6 shows the schematic of the coupled inductor boost converter and its key waveforms in CRM operation. If the turn’s ratio \( n \) is zero, i.e. \( N_2 \) is zero, it is identical to the conventional boost converter. Figure 7 shows the equivalent circuit for each mode. When the main switch \( Q \) turns on, \( i_Q(t) \) increases with the slope of \( V_{BAT} \) over \( L_1 \), resulting in the built-up of energy in \( L_1 \). Since the voltage across the secondary turns \( N_2 \) is \( nV_{BAT} \), the diode voltage \( V_D(t) \) is \( V_O+nV_{BAT} \), as shown in Figure 6 (b). After \( Q \) turns off, the voltage across the total inductor \( L_{eq} \) becomes \( V_O/V_{BAT} \), so that the diode current \( i_D(t) \) decreases with the slope of \( V_O/V_{BAT} \) over \( L_2 \). Since the voltage across the primary turns \( N_1 \) is \( N_1(V_O/V_{BAT}) \) over \( N_1+N_2 \), the switch voltage \( V_Q(t) \) is \( (N_1V_O+N_2V_{BAT}) \) over \( N_1+N_2 \), lower than \( V_O \) when \( N_2 \) is greater than \( N_1 \) for high voltage conversion ratio.
The peak current of the switch (I_{Q,PK} or I_{PK}) is obtained as follows:

\[ I_{PK} = \frac{V_{BAT}}{L_1} dT_s \]  

(8)

Due to the CRM operation, the peak current of the diode (I_{D,PK}) is obtained as follows:

\[ I_{D,PK} = \frac{V_o - V_{BAT}}{L_{eq}} (1 - d)T_s = \frac{V_o - V_{BAT}}{(1 + n)^2 L_1} (1 - d)T_s \]  

(9)

Since the output voltage is obtained as Equation (7), I_{D,PK} can be expressed with I_{PK} as follows:

\[ I_{D,PK} = \frac{1+n}{1+d} \frac{V_o - V_{BAT}}{V_{BAT}} \frac{(1 - d)T_s}{(1 + n)^2 L_1} = \frac{I_{PK}}{1 + n} \]  

(10)

According to Equation (7), the voltage conversion ratio depends on the turn’s ratio of the coupled inductor. If the turn’s ratio is 3, the voltage gain becomes more than 10 for 0.7 of the duty cycle. It will be also decreased when the copper loss of the inductor is considered. Nevertheless, it is large compared to the conventional boost converter. Thus, it is possible to make a sufficient output voltage from a low-voltage battery to drive the piezoelectric actuator by tuning the turn’s ratio. As can be seen in Figure 6, the voltage stress on the main switch is much lower than the conventional one. Therefore, the switching losses especially capacitive discharging losses can be reduced. However, the peak current of the main switch is 1+n times larger than the conventional one, which is one of the disadvantages of this topology. In addition, the voltage stress of the diode is increased as well.

**Design Procedure**

In this section, a design procedure for the coupled inductor boost converter using FAN8831 is presented with the specifications as follows:

- Nominal Input Voltage: 3.0 V_{DC} (Battery)
- Input Voltage Range: 2.7 ~ 3.3 V_{DC}
- Switching Frequency: 350 kHz at Full Load
- Output: 60 V_{DC}/25 mA (1.5 W)

The FAN8831 provides Zero Current Detection (ZCD) function allowing the next switching at the moment the inductor current becomes zero. Thus the desired operation mode is CRM.
[STEP-1] Determine Turns Ratio and Duty Cycle

For prevent absolute maximum voltage in operating condition, the switching voltage \( V_{LX} \) should be lower than 35 V, as can be seen in Figure 8.

\[
V_{LX} = V_{Q,DS} = V_{BAT} + \frac{V_O - V_{BAT}}{n+1} = \frac{V_O + nV_{BAT}}{n+1} \quad (11)
\]

Therefore, the turn’s ratio can be calculated as follows:

\[
n = \frac{V_O - V_{LX}}{V_{LX} - V_{BAT}} \quad (12)
\]

To determine the turn’s ratio, the input voltage variation has to be considered as well.

After getting the turn’s ratio of the coupled inductor, the duty cycle can be determined using Equation (7) as follows:

\[
d = \frac{G-1}{G+n} \quad (13)
\]

(Design Example) To get \( V_{LX} \) of 16 V using Equation (12), the turns ratio is calculated as follows:

\[
n_{\text{max}} = \frac{V_O - V_{LX}}{V_{LX} - V_{BAT,\text{max}}} = \frac{60-16}{16-3.3} = 3.46
\]

\[
n_{\text{min}} = \frac{V_O - V_{LX}}{V_{LX} - V_{BAT,\text{min}}} = \frac{60-16}{16-2.7} = 3.3
\]

Thus the turn’s ratio is selected as 4. Then the duty cycle is obtained using Equation (13).

\[
d_{\text{max}} = \frac{V_O - 1}{V_{BAT,\text{min}} + n} = \frac{60-1}{2.7 + 4} = 0.81
\]

\[
d_{\text{min}} = \frac{V_O - 1}{V_{BAT,\text{max}} + n} = \frac{60-1}{3.3 + 4} = 0.77
\]

Nominal 0.79 is the duty cycle of the converter when the input voltage is 3 V.

Like the conventional boost converter, the voltage conversion ratio or voltage gain of the coupled inductor boost converter is also limited due to the conduction losses in the used inductors. It is more considerable since the ESR of the coupled inductor is larger than the conventional one due to more turns. The voltage conversion ratio of CCM or CRM operation with the ESR of the boost inductor is obtained as follows:

\[
\frac{V_O}{V_{\text{BAT}}} = \frac{1 + nd}{1 - d} \left( \frac{r_1}{R(1-d)} + \frac{r_d(1+n)^2}{R(1-d)^2} \right) \quad (14)
\]

where \( R \) is the load resistance, \( r_1 \) is the primary side ESR and \( r_d \) is the sum of \( r_1 \) and the secondary side ESR, \( r_2 \), as depicted in Figure 8. As can be seen in Equation (14), the decreasing factor becomes significant as the turns ratio of the coupled inductor increases to obtain the high voltage conversion ratio. Figure 9 shows Equation (14) in a graphical way with \( n=7 \), \( R=5.500 \Omega \) and \( r_1=1.5 \Omega \), 3.0 \( \Omega \), and 5.0 \( \Omega \) as examples.

[STEP-2] Find Magnetizing Inductances

In CRM operation, the magnetizing inductance of the coupled inductor can be obtained from the slope of the inductor current, as shown in Figure 10. During \( t_{\text{OFF}} \), the inductor current flows through the diode and its average over one switching period is equivalent to the load current, \( I_{\text{OUT}} \) which is given as a specification. The average of the diode current is calculated as follows:

\[
I_{\text{OUT}} = \frac{I_{D,PK} \times (1-d)}{2} \quad (15)
\]
Therefore, the diode peak current is expressed as follows:

\[ I_{D,PK} = \frac{2I_{OUT}}{1 - d} \] (16)

According to Equation (10), the peak current of the main switch is obtained as follows:

\[ I_{PK} = \frac{2I_{OUT}(1 + n)}{1 - d} \] (17)

Combining Equations (17) and (8) yields

\[ L = \frac{V_{BAT}dT_S}{I_{PK}} = \frac{V_{BAT}d(1 - d)T_S}{2I_{OUT}(1 + n)} \] (18)

To get more exact equation for the inductance, the system efficiency has to be considered. There are lots of loss factors in the converter such as the ESR of the inductor, MOSFET’s turn-on resistance, diode’s forward drop, the non-ideal coupling of transformer, and so on. For all kinds of the loss terms, it could be divided into two categories. The first is the losses after transformer in view point of the power flowing like diode’s forward drop and including the transformer loss itself. In this case, the peak current required in Equation (17) should be increased to carry not only the output power but also the loss terms. On the other hand, the diode peak current calculated in Equation (16) is not changed since the output load current is kept constant regardless of the loss terms. Therefore, this loss factors related transformer and diode on the turn’s ratio so that \( I_{PK} \) and \( L_1 \) in Equations (17) and (18) should be modified as follows:

\[ I_{PK} = \frac{2I_{OUT}(1 + n)}{1 - d} \] (19)

\[ L = \frac{V_{BAT}dT_S}{I_{PK}} = \frac{V_{BAT}d(1 - d)T_S}{2I_{OUT}(1 + n)} \] (20)

where \( \eta \) is the expected efficiency of the system, generally 0.7~0.8.

The second category is the losses before transformer like the ESR of the inductor and \( R_{DS(on)} \) of the MOSFET. Due to these losses the practical peak current of the switch is lower than the expected. As the inductor current increases, the voltage drops on the ESR and \( R_{DS(on)} \) increases as well. The voltage applied on \( L_1 \) is reduced as time goes during \( t_{ON} \) so that the slope of the switch current decreases more and more, shown in Figure 11.

**Figure 10. Current Waveform of the Coupled Inductor**

Using the inductance \( L_1 \) calculated with Equation (20) is expected to make the peak switch current reach to \( I_{PK} \) during \( t_{ON} \), as plotted in dotted line in Figure 11. The peak switch current \( I_{PK} \) is obtained from Equation (19), which allows the specified load current to be supplied during \( t_{OFF} \). Due to the ESR and \( R_{DS(on)} \), however, the slope of the inductor current decreases as the inductor current increases so that the real peak current of the inductor is lower than \( I_{PK} \) originally targeted, as depicted in a blue solid curve in Figure 11. The real trajectory of the inductor current with ESR, \( r_1 \) and \( R_{DS(on)} \) can be expressed as follows:

\[ i_L(t) = \frac{V_{IN}}{r_1 + R_{DS(on)}} \left( 1 - e^{-\frac{r_1 + R_{DS(on)}}{t_{ON}}} \right) \] (21)

To make the red solid curve in Figure 11 to get required \( I_{PK} \) at \( t = t_{ON} \), the following equation is obtained.

\[ I_{PK} = \frac{V_{IN}}{r_1 + R_{DS(on)}} \left( 1 - e^{-\frac{r_1 + R_{DS(on)}}{t_{ON}}} \right) \] (22)

Therefore, the inductance is calculated to guarantee the required \( I_{PK} \) as follows:

\[ L_1 = \frac{(r_1 + R_{DS(on)}) \cdot t_{ON}}{\ln \left( \frac{I_{PK}(r_1 + R_{DS(on)})}{V_{IN}} \right)} \] (23)

To conclude, if all loss terms are taken into account, calculate the required \( I_{PK} \) using Equation (19) first, then calculate the inductance \( L_1 \) using Equation (23). On the other hand, it is enough to use Equations (17) and (18) when all losses are negligible.

**Design Example** Assuming the expected efficiency is 80%, the required peak current of the main switch is obtained as follows:

\[ I_{PK} = \frac{2I_{OUT}(1 + n)}{1 - d} = \frac{2 \cdot 25 m \cdot (1 + 4)}{1 - 0.79} = 1.52 [A] \]

According to the datasheet of the FAN8831, the \( R_{DS(on)} \) of the MOSFET is 600 mΩ. Assuming the ESR of the inductor \( r_1 \) is 300 mΩ, the inductance is calculated as follows:
$L_1 = -\frac{(\tau_i + R_{DS(on)}) \cdot I_{ON}}{\ln \left(1 - \frac{I_{PK} (\tau_i + R_{DS(on)})}{V_{IN}}\right)}$

$= -\frac{(0.3 + 0.6) \cdot 0.79}{350 \cdot (3)} = 3.34 [\mu H]$

Let’s select 3.3 $\mu$H. Therefore, $L_2$ is obtained as follows:

$L_2 = n^2L_1 = 4^2 \cdot 3.3 = 52.8 [\mu H]$

**[STEP-3] Voltage and Current Stresses on the Main Switch and the Diode**

As mentioned in STEP-1, the voltage stress on the main switch equals to $V_{LX}$. $V_{LX}$ voltage obtained from Equation (11), as can be seen in Figure 12.

**Figure 12. Inductor Current and Main Switch’s Drain Voltage**

The current stress on the main switch is the rms (root-mean-square) value of the dark area in Figure 12 as follows:

$L_s = -\frac{(\tau_i + R_{DS(on)}) \cdot I_{ON}}{\ln \left(1 - \frac{I_{PK} (\tau_i + R_{DS(on)})}{V_{IN}}\right)}$

(24)

Compared to the conventional boost converter, the voltage stress is reduced approximately by $1+n$ and the current stress is increased by $1+n$, which is a kind of trade-off.

The voltage and current stresses on the diode are obtained simply as follows:

$V_{D,PK} = V_O + nV_{BAT}$

$I_{D,ave} = I_{OUT}$

(25)

**[Design Example]** The $V_{LX}$ value calculated using Equation (11) as follows:

$V_{LX} = V_{O,DS} = \frac{V_O + nV_{IN,max}}{n + 1} = \frac{60 + 4 \cdot 3.3}{4 + 1} = 14.64 [V]$

The current stress of the main switch is as follows:

$I_{D,ave} = I_{PK} \sqrt{\frac{d}{3}} = \sqrt{\frac{0.79}{3}} = 0.78 [A]$

The integrated MOSFET in FAN8831 has the absolute voltage rating of 36 V which is enough to cover the voltage stress of 24 V with consideration of the derating of 80%. In addition, $R_{DS(on)}$ of the integrated MOSFET is maximally 500 mΩ, so that the expected conduction loss on it is around 0.4 W which is acceptable.

The voltage stress of the diode is as follows:

$V_{D,PK} = V_O + nV_{IN} = 60 + 4 \cdot 3.3 = 73.2 [V]$

The average current of the diode is as follows:

$I_{D,ave} = I_{OUT} = 25 [mA]$

A diode with more than 100 V of the voltage rating for the output diode should be selected.

**[STEP-4] Determine Output Capacitance**

The value of the output capacitor can be selected based on the output voltage ripple requirements. Without consideration of the effect of Effective Series Resistance (ESR) of the electrolytic capacitors as output capacitors, the output voltage ripple in a peak-to-peak manner is obtained as follows:

$V_{ ripple,pp} = \left( \frac{2d + (1-d)^2}{2} \right) I_{OUT} \cdot T_s$

(26)

where $V_{ ripple,pp}$ is the output voltage ripple in peak-to-peak manner. Therefore, the output capacitance can be selected with the given output voltages ripple specification as follows:

$C_O \geq \left( \frac{2d + (1-d)^2}{2} \right) I_{OUT} \cdot T_s$

(27)

On the other hand, it needs to check the required ESR, depending on the output voltage ripple specification, as calculated in Equation (29).

$ESR \leq \frac{V_{ripple,pp}(1-d)}{2I_{OUT}}$

(28)

After finding an appropriate capacitor with the calculated ESR; compare its capacitance with the result from Equation (27) and select larger one.

**[Design Example]** If the output voltage ripple is required to be less than 5% of the rated value, i.e. 3 V, then the output capacitance should be greater than:

$C_O \geq \left( \frac{2d + (1-d)^2}{2} \right) I_{OUT} \cdot T_s$

$= \left( \frac{2 \cdot 0.79 + (1-0.79)^2}{2} \right) \frac{25m}{350} \cdot 2 \times 3$

$= \frac{18.7 [nF]}{2}$

Meanwhile, the ESR of the output capacitor should be less than 13.5 Ω:
The electrolytic capacitor cases as a rule of thumb, the required capacitance is about 3.6 µF. Therefore, 3.6 µF is selected (at least). To get an optimal capacitance value, refer to the electrolytic capacitor datasheet that provides the allowable rms current.

On the other hand, if a ceramic capacitor is used as the output capacitor due to the limited space, it is no need to take its ESR into account. Select the capacitance to achieve a sufficient output voltage ripple according to Equation (27) only. In this example, 2.2 µF of a ceramic capacitor is selected as the output capacitor.

[STEP-5] ZCD Circuit Design

The Zero Current Detect (ZCD) pin of FAN8831 is to detect the instant when the boost inductor current runs dry for Zero Voltage Switching (ZVS) operation of the main switch. Once the boost inductor current becomes zero, the output capacitor of the main MOSFET (Coss) and the magnetizing inductor of the coupled inductor (Lm) resonate together, and the drain voltage of the main switch decreases, as shown in Figure 13.

Since the ZCD pin can be connected to the drain pin of the main switch due to its low voltage stress, FAN8831 can notice when the drain voltage reaches its minimum value directly. The threshold voltage to detect the drain voltage inside the ZCD pin is 1.83 V typically. Therefore, the next switching begins after the drain voltage of the main switch reaches 1.83 V. It also has 200 ns maximum delay time to the next gate turn-on, guaranteeing the minimum ZVS operation of the main switch.

The internal clamping circuit allows the voltage on ZCD pin to limit between 3.5 V and 0.12 V, typically. To limit the current in the clamping circuit, a resistor should be connected between the drain pin of the main switch and the ZCD pin. The resistor limits the negative current when the ZCD pin is clamped to 3.5 V (VCLAMPH) with the maximum drain voltage. It limits the positive current also when the ZCD pin is clamped to 0.12 V (VCLAMPL) with the minimum drain voltage in resonant manner.

The resistor RZCD is obtained as follows:

\[
R_{ZCD} \geq \frac{V_o + nV_{BAT,max} - V_{CLAMPH}}{1+n} \]

(29)

\[
R_{ZCD} \geq \frac{V_o - (2+n)V_{BAT,max} - V_{CLAMPH}}{1+n} \]

(30)

where \( V_{CLAMPH} \) is the input high clamp voltage, \( V_{CLAMPL} \) is the input low clamp voltage, \( I_{ZCD,SR} \) is the source current capability, and \( I_{ZCD,SK} \) is the sink current capability, described in the datasheet of FAN8831. \( R_{ZCD} \) should be selected as the highest one from Equations (29) and (30).

(Design Example) The minimum \( R_{ZCD} \) is determined as:

\[
R_{ZCD} \geq \frac{60 + 4 \cdot 3.3}{1+4} - 
\frac{60 + (2+4) \cdot 3.3}{1+4} = 4.84 \text{ [kΩ]}
\]

\[
R_{ZCD} \geq \frac{2.3m}{1+4} = 3.44 \text{ [kΩ]}
\]

Therefore, \( R_{ZCD} \) should be selected as 4.7 kΩ at the ZCD received from \( V_{LX} \), not to exceed the current capability of FAN8831.

On the other hand, if ZCD signal received from anode terminal of the switching diode, \( R_{ZCD} \) is determined as:

\[
R_{ZCD} \geq \frac{(V_{DRV} + 0.7) - V_{CLAMPH}}{I_{ZCD}}
\]
[STEP-6] Compensation Network Design

[Current Mode Control]
The duty cycle of the main switch is produced by comparing a control signal reflecting the system output voltage with an internal sawtooth waveform in voltage-mode control, while the inductor current or main switch current is sensed and directly compared to the control signal in current-mode control.

Current-mode control has two feedback loops: the output voltage is compared to a reference voltage and its error signal is applied to the input of a compensator in outer loop. The output of the compensator is compared to the current of the main switch and produces an appropriate duty cycle of the main switch in inner loop. There are usually three types of current-mode control methods: peak, average, and hysteresis current-mode control.

One of the advantages of current-mode control is a good line regulation. The change of the input line voltage is reflected to the slope of the main switch directly so the duty cycle of the main switch is changed directly as well.

Moreover, when operating in CRM or DCM, since there are no sub-harmonic oscillation problem in duty ratio D>0.5 and a simple single-pole transfer function without the right half-plane zero, it is easier to control the converter system.

[Feedback Loop Compensation Design]
The compensation network to stabilize the system could be either Type-I configuration (a simple integrator) or Type-II (an integrator with additional pole-zero pair). The type of the compensation circuit is selected according to the gain and the phase of the transfer function of the power plant at the crossover frequency.

Figure 14 shows the internal block diagram and the vicinity of the FAN8831 with Type-II compensator for regulating the output voltage of a coupled-inductor boost converter.

\[ \hat{i}_c(s) = \frac{1}{R_s} \cdot \frac{R_{FB1}}{R_{FB1} + R_{FB2}} \cdot g_m \cdot Z_{comp}(s) \]  

where:

\[ Z_{comp}(s) = \frac{1}{sC_z} \pm \frac{1+sR_zC_z}{1+sR_zC_p} \]

\[ R_s = \text{Internal sensing resistor} = \frac{V_{RAMP,F}}{I_{OCP}} \]

\[ f_z = \frac{1}{2(G+n)} \]

\[ r_z = R_o \left( \frac{G+n}{G} \right) \]

\[ G_{mB} = \frac{R_o}{2} \left( \frac{1}{2G+n} \right) \]

\[ \frac{1}{\omega_p} = \frac{1}{R_oC_o} \left( \frac{2G+n}{G+n} \right) \]

\[ G = \frac{V_o}{V_{IN}} \]

\[ n = \frac{N_2}{N_1} \]

Combining the above equations gives the following:

\[ v_c(s) = -\hat{i}_c(s) \times R_s \]  

\[ v_{comp}(s) = \hat{i}_{comp}(s) \times Z_{comp}(s) \]  

\[ \hat{i}_{comp}(s) = v_{comp}(s) \times g_m = \left( v_o(s) \times \frac{R_{FB2}}{R_{FB1} + R_{FB2}} \right) \times g_m \]  

Figure 14. Internal Block Diagram and Compensation Gain for Regulating the Output Voltage for FAN8820

Equations (31) ~ (33) are obtained from Figure 14.

Example 1: Determine the output voltage of a coupled-inductor boost converter. The control-to-output transfer function \( G_o(s) \), ignoring the effective-series-resistor ESR of the output capacitor, is:

\[ G_o(s) = \frac{v_o(s)}{i_c(s)} = \frac{f_z}{r_z} \left( \frac{1/sC_o}{1/\omega_p} \right) = \frac{G_{mB}}{G_{mB} + 1/sC_p} \]  

where:

\[ f_z = \frac{1}{2(G+n)} \]

\[ r_z = R_o \left( \frac{G+n}{G} \right) \]

\[ G_{mB} = \frac{R_o}{2} \left( \frac{1}{2G+n} \right) \]

\[ \frac{1}{\omega_p} = \frac{1}{R_oC_o} \left( \frac{2G+n}{G+n} \right) \]

\[ G = \frac{V_o}{V_{IN}} \]

\[ n = \frac{N_2}{N_1} \]

The procedure to design the feedback loop is as follows:

1. Obtain the control-to-output transfer function of the power stage using Equation (36). It is one-pole system whose pole frequency is \( \omega_p \) with the DC gain of \( G_{cut} \).

2. Determine the crossover frequency (\( f_c \)) around more than 10 times the pole frequency. Since the closed loop gain has -40 dB/dec slope and -180° of phase shift at the crossover frequency, as shown in Figure 16, it is required to place a zero of the compensation network (\( f_z \)) around the crossover frequency in order to improve the phase margin.
to maximize the bandwidth of the closed loop gain function so that 45° of phase margin is obtained.

(3) Place a pole of the compensation network \( f_p \) at least a decade higher than \( f_c \) to ensure that it does not affect the phase margin of the compensated system. It should also be sufficiently lower than the switching frequency of the system so the switching noise can be attenuated.

![Figure 16. Compensation Network Design](image)

The voltage divider network of \( R_{F1} \) and \( R_{F2} \) should be designed for the output voltage to meet the internal reference voltage \( V_{REF} (=1 \text{ V}) \) as follows:

\[
V_o = V_{REF} \left( 1 + \frac{R_{F1}}{R_{F2}} \right)
\]

### (Design Example) Find the control-to-output transfer function of the power stage. The parameters in the previous examples are summarized in the table below.

<table>
<thead>
<tr>
<th>Parameters</th>
<th>Value</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{IN} )</td>
<td>3 V</td>
</tr>
<tr>
<td>( V_O )</td>
<td>60 V</td>
</tr>
<tr>
<td>( I_{OUT} )</td>
<td>25 mA</td>
</tr>
<tr>
<td>( C_O )</td>
<td>0.33 ( \mu )F</td>
</tr>
<tr>
<td>( N )</td>
<td>4</td>
</tr>
<tr>
<td>( R_S )</td>
<td>1.12 ( \Omega )</td>
</tr>
<tr>
<td>( g_m )</td>
<td>800 ( \mu )Aho</td>
</tr>
<tr>
<td>( f_s )</td>
<td>350 kHz</td>
</tr>
</tbody>
</table>

If \( R_{F1} = 560 \text{ k}\Omega \), then \( R_{F2} \) is:

\[
R_{F2} = \frac{V_{REF} \times R_{F1}}{V_o - V_{REF}} = \frac{1 \times 560 \times 10^4}{(60 - 1)} = 9.5 \text{ [k}\Omega \text{]}.
\]

G, \( V_o \), \( f_c \), and \( f_z \) are calculated as follows:

\[
G = \frac{V_o}{V_{IN}} = \frac{60}{3} \approx 20,
\]

\[
R_o = \frac{V_o}{I_{OUT}} = \frac{60}{0.025} = 2.4 \text{ [k}\Omega \text{]},
\]

\[
f_z = \frac{1}{2} \left( \frac{1}{G + n} \right) = \frac{1}{2} \left( \frac{1}{2(20 + 4)} \right) \approx 0.0208,
\]

\[
r_z = R_o \left( \frac{G + n}{G} \right) = 240 \left( \frac{20 + 4}{20} \right) \approx 2.88 \text{ [k}\Omega \text{]}.
\]

The DC gain \( G_{z0} \) and frequency of the pole are calculated as follows:

\[
G_{z0} = \frac{R_o}{2} \left( \frac{1}{2G + n} \right) = \frac{1}{2} \left( \frac{1}{2 \times 20 + 4} \right) \approx 27.3 = 28.71 \text{ [dB]},
\]

\[
f_p = \frac{1}{2\pi R_0 C_o} \left( \frac{2G + n}{G + n} \right) = \frac{1}{2\pi \times 2.4k \times 0.33\mu} \left( \frac{2 \times 20 + 4}{20 + 4} \right).
\]

Next, design the compensation network. Place the crossover frequency of the compensated system at 800 Hz, about more than 10 times the pole frequency of the coupled-inductor boost converter. The gain of the uncompensated power stage at 800 Hz is calculated as follows:

\[
G_{z0 \, \text{at} \, 800 \text{ Hz}} = 28.71 - 20 \times (\log(800) - \log(55.3)).
\]

Since the DC gain of the compensator should be -5.5 dB at 800 Hz, \( R_z \) can be obtained as follows:

\[
R_z = R_z \left( \frac{K_{F1} + K_{F2} \times 10^{-5}}{R_{F2}} \right).
\]

If choose the \( R_z \) is 47 \( \text{k}\Omega \). \( C_z \) is obtained as follows:

\[
C_z = \frac{1}{2\pi R_z \times f_z} = \frac{1}{2\pi \times 47k \times 800} \approx 4.2 \text{ [n}\text{F]}.
\]

Let the frequency of the pole of the compensator placed at 8 kHz be a decade higher than the zero. \( C_p \) is obtained as follows:

\[
C_p = \frac{1}{2\pi R_z \times f_z} = \frac{1}{2\pi \times 47k \times 8k} \approx 423 \text{ [p}\text{F]}.
\]

The below shows the result of the compensation network design.
[STEP-7] Input Signal Frequency Setting

The FAN8831 is needed the INPUT pulse signal for the sinusoidal waveform drive of the Piezoelectric actuator as shown in Figure 17. The outputs are stops immediately when the input signal is not applied. Its valid input signal frequency range is from 20 Hz to 1000 Hz.

The frequency of sine wave can be determined using Equation (39) as follows:

\[ f_{\text{PIEZO}} = \frac{f_{\text{INPUT}}}{2} \quad (39) \]

A test point connected to INPUT of the SIGNAL connector is located next to TP11. The internal sine reference signal is generate by 6-bit DACs were used which were frequency controlled by external pulse input signal (INPUT).

![Figure 17](image-url) (a) Timing Chart, (b) Schematic of using External PWM Input

(Design Example) Assumed frequency of Piezoelectric driving voltage is 100 Hz when used the external pulse input, the required frequency of the input signal is obtained as follows:

\[ f_{\text{INPUT}} = 2 \times f_{\text{PIEZO}} = 2 \times 100 = 200 \text{[Hz]} \]

If when using the timer IC like as LM555, The frequency of oscillation can be determined using equation as follows:

\[ f_{\text{INPUT}} = \frac{1}{(1.4 \times R17 \times C12)} \]

If choose the timing capacitor C12 is 100 nF, the timing resistor R17 is obtained as follows;

\[ R17 = \frac{1}{(1.4 \times 200 \times 100 \text{nF})} \approx 35.7 \text{[kHz]} \]

Where R17= R20 + R21

[STEP-8] Programmable OCP Trip Level Setting

The peak current level (\( I_{\text{OVP}} \)) of boost switch is programmed via external resistor (R8) and the maximum value is limited typically 1.8 A. The programmed current limit should be less than the rated saturation limit of the inductor selected by the user to avoid damage to both the inductor and the FAN8831. The peak current limit level is according to the \( R_{\text{OCP}} \) (R8) values as show the Figure 18.

![Figure 18](image-url) Characteristic Graph of \( I_{\text{OVP}} \) vs. \( R_{\text{OCP}} \)

[STEP-9] Over-Voltage Protection Setting

The FAN8831 features unique \( V_{\text{DRV}} \) monitoring to maximize safety when the feedback voltage is higher than the specified threshold voltages as shown in Figure 18. The OVP comparator shuts down the output drive block when the voltage of FB pin is higher than 1.1 V and there is 0.1 V for hysteresis. If output voltage exceeds its rated output, the output capacitor (C3 and C4) may be damaged. To prevent this, an additional OVP pin is assigned to double-check output voltage when FB pin is shorted ground or open conditions. The additional OVP is called “second” OVP, while FB pin OVP is called “first” OVP. The second OVP level \( (V_{\text{OVP}}) \) is programmed via three external resistors as shown in Figure 19. If the second OVP function is not used, the OVP pin must be connected to the FB pin or to the ground.

![Figure 19](image-url) Boost Converter Over Voltage Setting

(Design Example) Choose the over-voltage trip level is 70 V. If R12 is 560 kΩ, then R13+R14 is:

\[ R13 + R14 = \frac{V_{\text{OVP}} \times R12}{V_{\text{OVP}} - V_{\text{OVP}} \text{sat}} = \frac{1.15 \times 560 \times 10^3}{(70 - 1.15)} = 9.35 \text{[kΩ]} \]
[STEP-10] PWM Switching Frequency Setting
The frequency of sine PWM modulator can be controlled by RT (R11) values and the switching frequency is according to the RT (R11) values as shown in Figure 20.

![Figure 20. Characteristic Graph of PWM Frequency vs. RT Values](image)

**INPUT Signal Characteristics**
Measure the operating waveforms when frequency change of input pulse as shown in Figure 23.

![Figure 23. Operation Waveforms when the INPUT Signal Frequency Change](image)

[STEP-11] Sine Wave Amplitude Setting
The amplitude of sine wave can be controlled by R_{ADJ} (R9) values and the sine wave amplitude is according to the R_{ADJ} (R9) values as shown in Figure 21.

![Figure 21. Characteristic Graph of Sine Amplitude vs. R_{ADJ} and V_{ADJ}](image)

**Experimental Verification**
To show the validity of the design procedure presented in this application note, a prototype of the design example was implemented and tested. All the circuit components are used as designed in the design example.

**Startup Characteristics**
Measure the startup time interval between Enable and stable output at output peak to peak voltage 60 V with capacitive load as shown in Figure 22. Sine wave comes from 3rd rising edge of input pulse signal after when step-up DC-DC converter output voltage reaches the specified target level.

![Figure 22. Operation Waveforms during Startup Green(V_{PIEZO}), Red (V_{DRV}), Yellow (INPUT), Blue (ENABLE)](image)

![Figure 24. Characteristic Graph of FAN8831 feature have frequency of output voltage does not change even if change the duty cycle of the input signal](image)
AN-5081 APPLICATION NOTE

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Consideration of Output Filter

The class-D amplifier outputs are driven by heavy-duty in an H-bridge configuration. The result is a square-wave output signal with a duty cycle that is proportional to the amplitude of the internal sine reference signal. The output may be directly applied to the piezoelectric load. So, EMI is a consideration when used the class-D amplifier because of the piezoelectric is capacitive load.

The main goal of the output filter is attenuation of the high frequency switching noise of the class-D amplifier while preserving the signals in the sine wave driving as shown in Figure 25.

The switching frequency \( f_s \) of the class-D amplifier can influence the choice of the filter order — the higher the \( f_s \), the lower the order required to achieve a given attenuation within a specified pass band. This would seem to dictate the use of the highest switching frequency possible. The tradeoff is that increasing \( f_s \) increases the switching losses and the EMI, and decreases the efficiency of the amplifier.

\[
\frac{1}{2\pi R C_{\text{PIEZO}}} \leq f_s \leq \frac{1}{10 \times f_{\text{SINE}}} \leq \frac{f_s}{10}
\]  

where, \( R \) is \( R8+R10 \) and \( C_{\text{PIEZO}} \) is equivalent capacitance of Piezoelectric.

\( f_{\text{PIEZO,MAX}} = 500 \text{ Hz in FAN8831} \)

Peak output current from the Class-D Amplifier should therefore be limited to the maximum Piezo driving frequency:

\[
I_{\text{PEAK, DRIVER}} = \frac{V_{\text{DRVPEAK}}}{\sqrt{R^2 + X_C^2}}
\]

where, \( X_C \) is:

\[
X_C = \frac{1}{2\pi f_{\text{FILTER}} C_{\text{FILTER}}}
\]

The filter capacitors should be ceramic capacitors with X7R characteristics for stability over voltage and temperature.

The corner frequency of output filter, \( f_{\text{FILTER}} \), should be choose between larger than at least 10 times of sine wave frequency and less than 1/10 of PWM switching frequency in equation (46).

\[
10 \times f_{\text{SINE}} \leq f_{\text{FILTER}} \leq \frac{f_s}{10}
\]

Measure the voltage waveforms of piezoelectric actuator when not using an output filter capacitor (CF1 and CF2) or using an output filter capacitor to reduce the switching noise as shown in Figure 26.
Application Circuit Diagram and BOM List

Typical Application Circuit

List of Test Point

Table 1 shows the list of test point on evaluation board.

Table 1. List of Test Point of Evaluation Board

<table>
<thead>
<tr>
<th>TP</th>
<th>Reference</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>TP1</td>
<td>$V_{DD}$</td>
<td>Power supply of step-up DC-DC converter.</td>
</tr>
<tr>
<td>TP2</td>
<td>$V_{DRV}$</td>
<td>Power supply of full-bridge driver, (TP15, TP16)</td>
</tr>
<tr>
<td>TP3</td>
<td>FB</td>
<td>Step-up DC-DC converter output voltage feedback input.</td>
</tr>
<tr>
<td>TP4</td>
<td>LX</td>
<td>Switch node. This pin is connected to the inductor.</td>
</tr>
<tr>
<td>TP5</td>
<td>ZCD</td>
<td>The input of the zero current detection</td>
</tr>
<tr>
<td>TP6</td>
<td>COMP</td>
<td>Compensation network. Connected to the output of the voltage error amplifier</td>
</tr>
<tr>
<td>TP7</td>
<td>EN</td>
<td>Enable pin to turn on and off the step-up DC-DC converter, (TP10)</td>
</tr>
<tr>
<td>TP8</td>
<td>OCP</td>
<td>Sets Step-up DC-DC converter current limit</td>
</tr>
<tr>
<td>TP9</td>
<td>FO</td>
<td>Fault output. An open drain fault-out (FO) signal indicates if an over-voltage of dc-dc converter or thermal-shutdown has occurred</td>
</tr>
<tr>
<td>TP11</td>
<td>INPUT</td>
<td>PWM input signal for internal sine wave generation</td>
</tr>
<tr>
<td>TP12</td>
<td>ADJ</td>
<td>Output voltage adjust control pin. Connect to internal current source to change output voltage using an external resistor.</td>
</tr>
<tr>
<td>TP13</td>
<td>RT</td>
<td>Oscillator frequency control pin</td>
</tr>
<tr>
<td>TP14</td>
<td>OVP</td>
<td>Voltage sense input of Step-up DC-DC converter for Over-Voltage Protection</td>
</tr>
<tr>
<td>TP17</td>
<td>OUT1</td>
<td>Output 1 for full-bridge driver</td>
</tr>
<tr>
<td>TP18</td>
<td>OUT2</td>
<td>Output 2 for full-bridge driver</td>
</tr>
</tbody>
</table>
## Bill of Materials

<table>
<thead>
<tr>
<th>Item No.</th>
<th>Part Reference</th>
<th>Part Number</th>
<th>Qty.</th>
<th>Description</th>
<th>Manufacturer</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>U1</td>
<td>FAN8831</td>
<td>1</td>
<td>Controller</td>
<td>Fairchild</td>
</tr>
<tr>
<td>2</td>
<td>U2</td>
<td>LMC555</td>
<td>1</td>
<td>Timer IC</td>
<td>Fairchild</td>
</tr>
<tr>
<td>3</td>
<td>D2</td>
<td>ES1B</td>
<td>1</td>
<td>1 A/100 V Diode</td>
<td>Fairchild</td>
</tr>
<tr>
<td>4</td>
<td>D3</td>
<td>HSML-C197</td>
<td>1</td>
<td>LED</td>
<td>DIALIGHT</td>
</tr>
<tr>
<td>5</td>
<td>T1</td>
<td>NA-5880AE</td>
<td>1</td>
<td>3.3 μH Coupled-Inductor</td>
<td>Coil Craft</td>
</tr>
<tr>
<td>6</td>
<td>R1, R12</td>
<td>MCR01YRTF5603</td>
<td>2</td>
<td>560 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>7</td>
<td>R2</td>
<td>MCR01YRTF2002</td>
<td>1</td>
<td>20 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>8</td>
<td>R3</td>
<td>MCR01YRTF4702</td>
<td>1</td>
<td>47 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>9</td>
<td>R4</td>
<td>MCR01YRTF8201</td>
<td>1</td>
<td>8.2 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>10</td>
<td>R5</td>
<td>MCR01YRTF5102</td>
<td>1</td>
<td>51 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>11</td>
<td>R6</td>
<td>MCR01YRTF3001</td>
<td>1</td>
<td>3 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>12</td>
<td>R7</td>
<td>MCR01YRTF4300</td>
<td>1</td>
<td>430 Ω ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>13</td>
<td>R8</td>
<td>MCR01YRTF1202</td>
<td>1</td>
<td>12 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>14</td>
<td>R9, R11, R18</td>
<td>MCR01YRTF1003</td>
<td>3</td>
<td>100 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>15</td>
<td>R10, R14, R19</td>
<td>MCR01YRTF000</td>
<td>3</td>
<td>0 Ω ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>16</td>
<td>R15, R16</td>
<td>MCR18YRTF5101</td>
<td>2</td>
<td>5.1 kΩ ±1% Chip Resistor</td>
<td>Rohm or Equivalent</td>
</tr>
<tr>
<td>17</td>
<td>R13</td>
<td>MCR01YRTF8201</td>
<td>1</td>
<td>9.31 kΩ ±1% Chip Resistor</td>
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<tr>
<td>18</td>
<td>R17</td>
<td>3296X1-1-104</td>
<td>1</td>
<td>Variable Resistor</td>
<td>Boarns</td>
</tr>
<tr>
<td>19</td>
<td>R20, R21, R22, R23</td>
<td>OPEN</td>
<td>4</td>
<td>OPEN</td>
<td>OPEN</td>
</tr>
<tr>
<td>20</td>
<td>C1</td>
<td>C2012X5R0J226K125AB</td>
<td>1</td>
<td>6.3 V/22 μF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>21</td>
<td>C3</td>
<td>C3225JB2A225K230AB</td>
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<td>100 V/2.2 μF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>22</td>
<td>C5</td>
<td>CGJ4C2C0G1H151J060AA</td>
<td>1</td>
<td>50 V/150 pF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>23</td>
<td>C6</td>
<td>CGJ4C2C0G1H181J060AA</td>
<td>1</td>
<td>50 V/390 pF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>24</td>
<td>C7</td>
<td>C2012C0G1H222J060AA</td>
<td>1</td>
<td>50 V/3.9 nF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>25</td>
<td>C8</td>
<td>C2012C0G1H222J060AA</td>
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<td>50 V/2.2 nF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>26</td>
<td>C9</td>
<td>C2012C0G1H102J060AA</td>
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<td>50 V/1 nF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>27</td>
<td>C10</td>
<td>CGJ4C2C0G1H101J060AA</td>
<td>1</td>
<td>50 V/100 pF Chip Capacitor</td>
<td>TDK or Equivalent</td>
</tr>
<tr>
<td>28</td>
<td>C11</td>
<td>C2012JB1C105K085AA</td>
<td>1</td>
<td>16 V/1 μF Chip Capacitor</td>
<td>TDK or Equivalent</td>
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<tr>
<td>29</td>
<td>C12</td>
<td>CGJ4J2X7R1C104K125AA</td>
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<td>TDK or Equivalent</td>
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<tr>
<td>30</td>
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<td>4</td>
<td>OPEN</td>
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<tr>
<td>31</td>
<td>J1, J4</td>
<td>5268-02</td>
<td>2</td>
<td>Connector</td>
<td>Molex</td>
</tr>
<tr>
<td>32</td>
<td>J3</td>
<td>SS1290</td>
<td>1</td>
<td>Switch</td>
<td>Samyoung High Tech</td>
</tr>
</tbody>
</table>
Coupled-Inductor and Winding Specifications

- Turn ratio = \( N_p : N_s = 1:4 \)

![Coupled-Inductor and Wind Construction Image]

**Figure 28. Coupled-Inductor Specifications and Construction**

<table>
<thead>
<tr>
<th>No.</th>
<th>Winding</th>
<th>Pin (S → F)</th>
<th>Values [( \mu H )]</th>
<th>DCRMAX [( \Omega )]</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>( N_p )</td>
<td>1 → 2</td>
<td>2.64 3.96</td>
<td>0.306</td>
</tr>
<tr>
<td>2</td>
<td>( N_s )</td>
<td>4 → 3</td>
<td>38.8 59.2</td>
<td>2.30</td>
</tr>
<tr>
<td>3</td>
<td>Turn-Ratio</td>
<td>Np: Ns</td>
<td></td>
<td>1:4</td>
</tr>
<tr>
<td>4</td>
<td>Leakage</td>
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<tr>
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<td>Inductance</td>
<td></td>
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<tr>
<td></td>
<td></td>
<td>1 → 2</td>
<td>270 356</td>
<td>Short Pins 4 - 3</td>
</tr>
</tbody>
</table>

Measured by 100 KHz, 0.1 V\(_{\text{RMS}}\) 0 Adc

Recommended Inductor: CoilCraft NA5880-AE
References


Related Product Information

FAN8831 Product Folder

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